

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6211041").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:11
L2	67511	"SiC" "silicon carbide"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:11
L3	1	1 and 2	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:15
L4	1	1 and (polish polishing polished CMP)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:15
L5	67511	"SiC" "silicon carbide"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:22
L6	10208	5 with substrate	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:22
L7	1782	wafer with (cleave cleaving cleaved)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:23
L8	2847	wafer with (cleave cleaving cleaved split splitting)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:23
L9	209	6 and 8	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:23
L10	48743	ion adj implantation	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:23
L11	76	9 and 10	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:23
L12	61	11 and (polish polishing polished CMP)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:24
L13	27	12 not henley.in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:24
S1	12	(tolchinsky-peter-g shaheen-mohamad-a yablok-irwin).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:42
S2	2	S1 and SiC	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:43

S3	67387	"SiC" "silicon carbide"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:22
S4	48670	ion adj. implantation	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:23
S5	75629	heat with (dissipation sink)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:44
S6	1779	wafer with (cleave cleaving cleaved)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:23
S7	43	S3 and S4 and S5 and S6	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:44
S8	39	S7 and @ad<"20030925"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:44
S9	1544	(438/458,459,931).CCLS.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:47
S10	1390	S9 and @ad<"20030925"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 08:18
S11	5	((("5371037") or ("5374564") or ("5856229") or ("6258698") or ("6372609")).PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:48
S12	2	S3 and S11	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:49
S13	423	S10 and S4	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:49
S14	225	S13 and S3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:49
S15	27	S14 and S5	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/12 14:49
S16	90	Henley-Francois-J.in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 08:18
S17	89	S16 and @ad<"20030925"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:17
S18	49655	silicon adj. carbide	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:43

S19	31330	SIC	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:43
S20	65781	thermal adj conductivity	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:43
S21	13474	S18 and S19	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:43
S22	67511	S18 S19	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:43
S23	9077	S22 and S20	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:43
S24	4446	S22 same wafer	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:43
S25	809	S24 and S20	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:44
S26	419	S25 and (bond bonding bonded bonds)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:44
S27	370	S26 and @ad<"20030925"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:44
S28	48743	ion adj implantation	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:44
S29	73	S27 and S28	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:44
S30	15	S29 and (split splitting cleave cleaved cleaving)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:45
S31	90	Henley-Francois-J.in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:47
S32	89	S31 and @ad<"20030925"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:47
S33	0	S32 and S20	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:48
S34	15214	thermal adj properties	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:48

S35	575	S34 and silicon and SiC	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 10:02
S36	821	S34 same silicon	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:48
S37	172	S36 and SiC	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 09:49
S38	80	S37 and S20	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 10:01
S39	1494	S24 and table	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 10:01
S40	949	S39 and silicon and SiC	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:09
S41	1	("5849627").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:09
S42	67511	"SiC" "silicon carbide"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:09
S43	1	S41 and S42	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:09
S44	90	Henley-Francois-J.in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:26
S45	89	S44 and @ad<"20030925"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:28
S46	181	handle with carbide	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:18
S47	0	S45 and S46	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:18
S48	627	handle same carbide	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:18
S49	0	S48 and S45	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:18
S50	21	S45 and handle	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:18

S51	16	S50 and carbide	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:22
S52	2	((("6372609") or ("5374564"))).PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:23
S53	2	S52 and S42	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:23



S55	556	("1275192"   "1412743"   "2614055"   "3085454"   "3117022"   "3225820"   "3390033"   "3551213"   "3770499"   "3786359"   "3806380"   "3832219"   "3855110"   "3900636"   "3901423"   "3907107"   "3915757"   "3926147"   "3946334"   "3957107"   "3993909"   "4006340"   "4039416"   "4042128"   "4053335"   "4074139"   "4107350"   "4108751"   "4116751"   "4121334"   "4170662"   "4216906"   "4237601"   "4244348"   "4252837"   "4255208"   "4274004"   "4304983"   "4322661"   "4342631"   "4345968"   "4346123"   "4361600"   "4368083"   "4368523"   "4371412"   "4375125"   "4412868"   "4452644"   "4461783"   "4468309"   "4471003"   "4486247"   "4490190"   "4500563"   "4507605"   "4508056"   "4536657"   "4539050"   "4539505"   "4543465"   "4566403"   "4567505"   "4568563"   "4585945"   "4615298"   "4631576"   "4632719"   "4645546"   "4684535"   "4689985"   "4704302"   "4706377"   "4717683"   "4727047"   "4744833"   "4745337"   "4746394"   "4756882"   "4764394"   "4766086"   "4774194"   "4776022"   "4803332"   "4808546"   "4810935"   "4811684"   "4819038"   "4820222"   "4825201"   "4826646"   "4837172"   "4846928"   "4847792"   "4853250"   "4856693"   "4870357"   "4883561"   "4887005"   "4891118"   "4891329"   "4894709"   "4899105"   "4911814"   "4931405"   "4948458"   "4950377"   "4950956"   "4951601"   "4952273"   "4956693"   "4960073"   "4982090"   "4983251"   "4990546"   "4998677"   "5010579"   "5013563"   "5015352"   "5017755"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/14 13:27
Search History 4/14/05 3:30:28 PM C:\Documents and Settings\Wilson1\My Documents\EAST\Workspaces\10672968.wsp						

S56	931	S54 S55	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:28
S57	916	S56 and @ad<"20030925"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:28
S58	137	S57 and S42	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:28
S59	108	S58 and heat	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 13:28
S60	79	S59 and (polish polishing polished CMP)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/04/14 15:23



(FILE 'HOME' ENTERED AT 08:58:42 ON 14 APR 2005)

FILE 'INSPEC, CAPLUS' ENTERED AT 08:58:50 ON 14 APR 2005

L1 97890 S SILICON CARBIDE  
L2 124610 S SIC  
L3 144445 S L1 OR L2  
L4 101761 S THERMAL CONDUCTIVITY  
L5 3188 S L4 AND L3  
L6 90283 S ION IMPLANTATION  
L7 20 S L5 AND L6

FILE 'STNGUIDE' ENTERED AT 09:00:24 ON 14 APR 2005

FILE 'INSPEC, CAPLUS' ENTERED AT 09:01:57 ON 14 APR 2005

L8 23 S WAFER SPLITTING  
L9 124 S LAYER SPLITTING  
L10 143 S L8 OR L9  
L11 17 S L10 AND L3

FILE 'STNGUIDE' ENTERED AT 09:03:30 ON 14 APR 2005

FILE 'INSPEC, CAPLUS' ENTERED AT 09:09:29 ON 14 APR 2005

L12 338 S SMART CUT  
L13 3 S L12 AND L4

FILE 'STNGUIDE' ENTERED AT 09:10:24 ON 14 APR 2005

FILE 'INSPEC, CAPLUS' ENTERED AT 09:11:06 ON 14 APR 2005

L14 108 S L5 AND BONDING  
L15 12 S L14 AND WAFER